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selectively removing said second insulating layer so as to form element isolation regions
composed of the trenches filled with said second insulating layer;

removing said first insulating layer; and

a' emid. selectively removing said second insulating layer using a chemical mechanical polishing
(CMP) process until a surface of the conductive layer is substantially even with a surface of the
second insulating layer, the conductive layer being used as a stopping layer for the CMP process.
